semi

APM12-SERIES AUTOMOTIVE MODULE CASE MODBG

ISSUE B

DATE 16 DEC 2021

0.00 LEAD POSITION 0.40 A B в 8 14,20 6 1 5 L3 0.00 Ф Α 14.20 SIDE VIEW 6 8.35 MARK AREA 2X 🛛 A A3 ***** 12 h4 E1 E1/2 ╘╧┛ ╎┝╤╤┙ 10 11 TOP VIEW A2 С -L2 X3 h END VIEW 4.15 h 17.30 b3 35

b2 SIDE VIEW

* For additional Information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDER RM/D.

GENERIC **MARKING DIAGRAM***

ZZZ ATYWW NNNNNN

XXXX = Specific Device Code ZZZ = Lot ID = Assembly & Test Location = Year

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BOTTOM VIEW

Υ = Work Week WW

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6 4

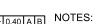
AT

NNN = Serial Number

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	APM12-SERIES AUTOMOTIVE MODULE		PAGE 1 OF 1	

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- 1. DIMENSIONING AND TOLERANCING PER. ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.

	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
⊠A	3.70	3.80	3.90
A2	4.60	4.80	5.00
A3	1.30	1.50	1.70
b	0.70	0.80	0.90
b1	1.25	1.35	1.45
b2	6.80	7.00	7.20
b3	6.70	6.90	7.10
b4	4.10	4.30	4.50
С	0.75	0.80	0.85
D	29.80	30.00	30.20
E1	22.60	22.80	23.00
L1	12.40	12.70	13.00
L2	7.50	7.80	8.10
L3	4.90	5.10	5.30
q	25.50	25.60	25.70

* WARPAGE(POINT 1,2,3,4 BASED ON 0) : 0~100um

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